

Nordson Electronics Solutions
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FOR RELEASE: Immediately
SEMICON West, Booth # 5845

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Nordson Electronics Solutions to Feature New Fluid Dispensing and Plasma Treatment Systems for Panel-Level Packaging at SEMICON West 2026

- See the new **ASYMTEK Vantage XL** dispensing system demonstrated in Booth 5845.
- Learn how the new **MARCH ExoSPHERE** plasma treatment system enables high-throughput panel-level packaging production.

High resolution image available at: <https://nordson.pub/PRvantXL26>

Carlsbad, CA, USA – 17 September 2026 – [Nordson Electronics Solutions](https://nordson.pub), a global leader in reliable electronics manufacturing technologies, will feature two new systems designed to address the demanding requirements of panel-level packaging (PLP) and other [advanced semiconductor packaging](#) applications. On exhibit will be the new [ASYMTEK Vantage XL](#) system, designed to meet throughput and yield demands driven by AI, high-performance computing, and advanced semiconductor packaging applications. Plasma experts will be available to discuss the new **MARCH ExoSPHERE** and how it enables PLP operations for higher throughput and lower manufacturing costs. Together, these systems help manufacturers accelerate process development and scale advanced packaging production with greater efficiency and control.



The new [ASYMTEK Vantage XL](#) system extends Nordson's proven Vantage platform for dispensing underfill onto larger panel formats, enabling manufacturers to develop next-generation advanced packaging processes and scale production with greater accuracy, throughput, and process control. The system was [first exhibited at SEMICON Taiwan](#) in

September 2026. New capabilities improve underfill flow and help mitigate panel warpage, delivering more consistent, void-free results.

The [MARCH ExoSPHERE plasma treatment](#) system supports panel and wafer-based advanced packaging processes with highly uniform surface preparation. The system enhances surface activation, cleaning, and adhesion, improving process consistency and supporting void-free underfill and other critical packaging applications. Its patented three-axis symmetrical chamber ensures consistent, uniform plasma treatment on panels up to 650x650mm. Tight process controls ensure repeatable results from panel to panel during production while integrated handlers accommodate panels and wafers, adapting for warpage.

Panel-level packaging (PLP) enables higher throughput and lower manufacturing costs than traditional wafer-based approaches, particularly as package sizes increase and demand grows for AI and high-performance computing applications. However, scaling to larger panel formats introduces significant challenges, including warpage control, thermal management, and process accuracy. Nordson's new ASYMTEK Vantage XL and MARCH ExoSPHERE systems are designed to help manufacturers overcome these challenges while improving productivity and yield.

Visit the Nordson booth # 5845 to find out more at [SEMICON West](#), October 13–15, 2026, Moscone Center, San Francisco, California, USA.

About Nordson Electronics Solutions

[Nordson Electronics Solutions](#) makes reliable electronics a reality. Through our ASYMTEK, MARCH, and SELECT brands, we supply the world's semiconductor, electronics, and precision assembly manufacturers with the innovative [fluid dispensing](#), [conformal coating](#), [plasma treatment](#), and [selective soldering](#) solutions their products need to protect sensitive electronics and deliver a lifespan of reliability. Day after day, year after year, across the globe, for over 40 years, we've provided engineering and applications excellence to help our customers succeed.

About Nordson Corporation

Nordson Corporation (NASDAQ: NDSN) is an innovative precision technology company that leverages a scalable growth framework through an entrepreneurial, division-led organization to deliver top tier growth with leading margins and returns. The Company's direct sales model and applications expertise serves global customers through a wide variety of critical applications. Its diverse end-market exposure includes consumer non-durable, medical, electronics and industrial end markets. Founded in 1954 and headquartered in Westlake, Ohio, the Company

has operations and support offices in over 35 countries. Visit Nordson on the web at www.nordson.com.

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